

规格书

Data Sheet

产品型号/PartNumber: T-B2835NW8CCG-5L

版本号/Version: REV.1

制定/Instituted By

审核/Checked By

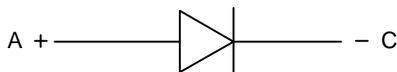
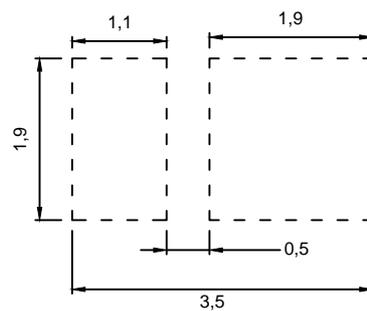
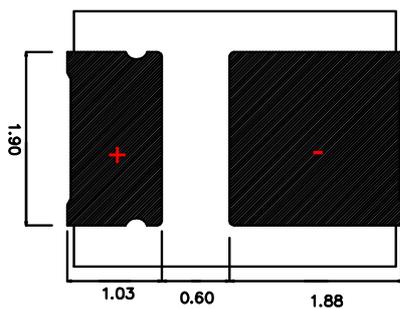
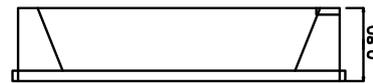
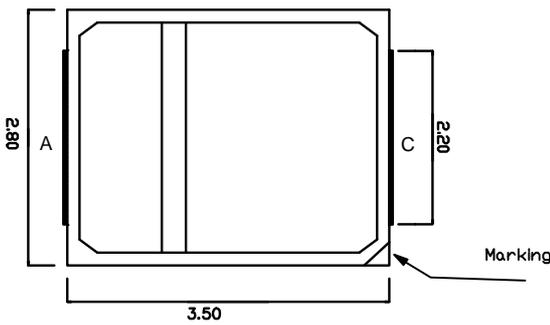
核准/Approvde By

客户料号/Customer PN:

客户承认栏/Customer Approval

产品描述 Features

- 颜色/Color: White
- 胶体/Lens: Yellow Diffused
- EIA 规范标准包装/EIA STD Package
- 环保产品, 符合ROHS要求/Meet Rohs, Green Product



注/Notes: 单位: 毫米 (mm) / All dimensions are in millimeters
公差: 如无特别标注则为 ± 0.2 mm Tolerance is ± 0.2 mm unless otherwise noted

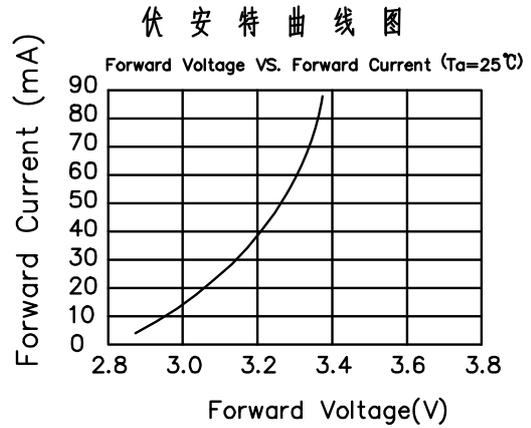
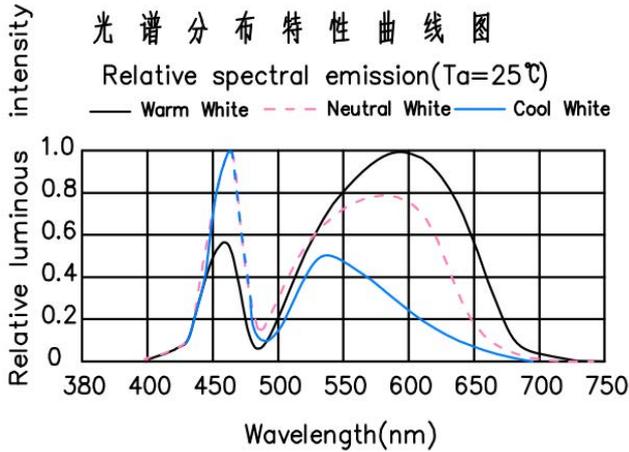
最大绝对额定值/ Absolute Maximum Ratings (Ta=25℃)

参数/ Parameter	符号/Symbol	最大额定值/ Rating	单位/Unit
消耗功率/ Power Dissipation	Pd	510	mW
最大脉冲电流/ Peak Forward Current(1/10占空比, 0.1ms脉宽)	IFP	200	mA
正向直流工作电流/DC Forward Current	IF	100	mA
反向电压/ Reverse Voltage	VR	5	V
工作环境温度 Operating Temperature Range	Topr	-40℃ ~ +90℃	
存储环境温度 Storage Temperature Range	Tstg	-40℃ ~ +90℃	
焊接条件 Soldering Condition	Tsol	回流焊/ Reflow soldering : 260℃ .10s 手动焊/ Hand soldering : 300℃ .3s	
抗静电能力 Electrostatic Discharge	ESD	2000	V

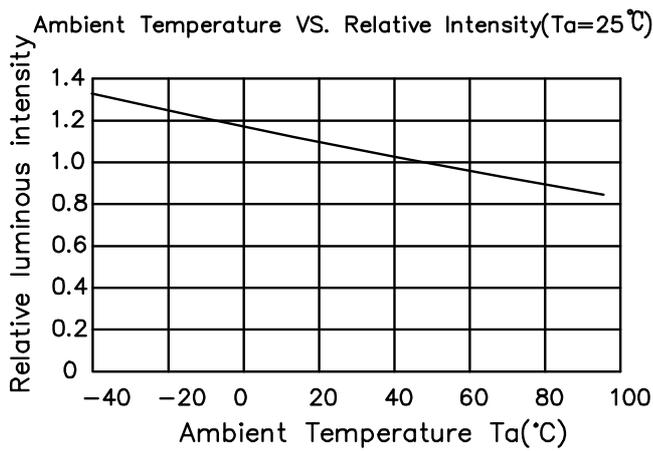
光电参数/ Electrical Optical Characteristics (Ta=25℃)

参数 Parameter	符号 Symbol	颜色 Color	最小值 Min	代表值 Typ	最大值 Max	单位 Unit	测试条件 Test Condition
光强 Luminous Intensity	Iv	W	28		35	LM	IF=100mA
峰值波长 Peak Wavelength	λp	W		5000		K	IF=100mA
主波长 Dominant Wavelength	λd	W	4500		5500	K	IF=100mA
显色指数 Color rendering index	Ra	W		80			IF=100mA
正向电压 Forward Voltage	VF	W	2.8		3.4	V	IF=100mA
半光强视角 Viewing Angle	2θ1/2			120		deg	IF=100mA
反向电流 Reverse Current	IR	R			5	uA	VR=5V

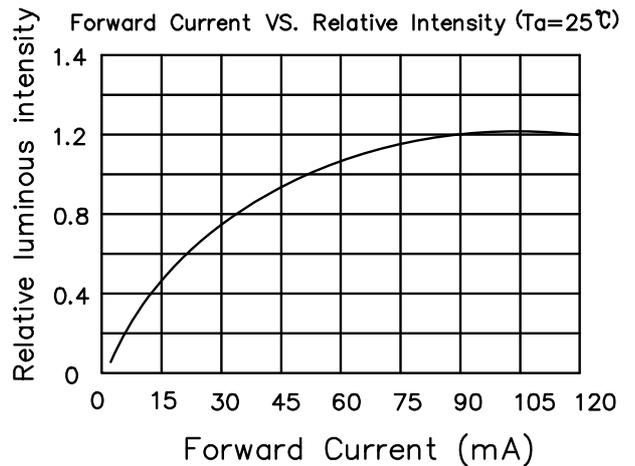
光电参数代表值特征曲线/ Typical Electrical-Optical Characteristics Curves



相对光强与环境温度特性曲线

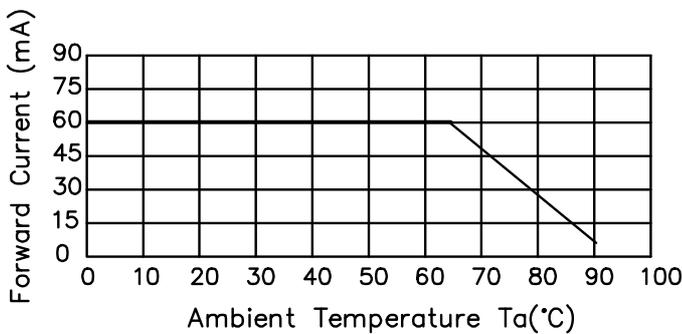


相对光强与电流特性曲线图



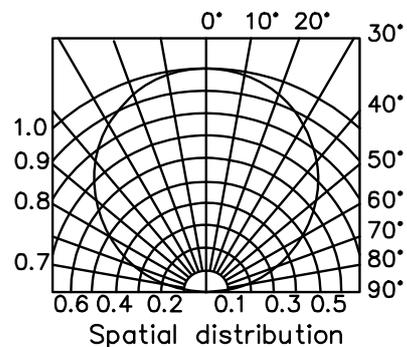
最大正向电流与环境温度特性曲线图

Maximum Forward current (Ta=25°C) vs. Ambient Temperature

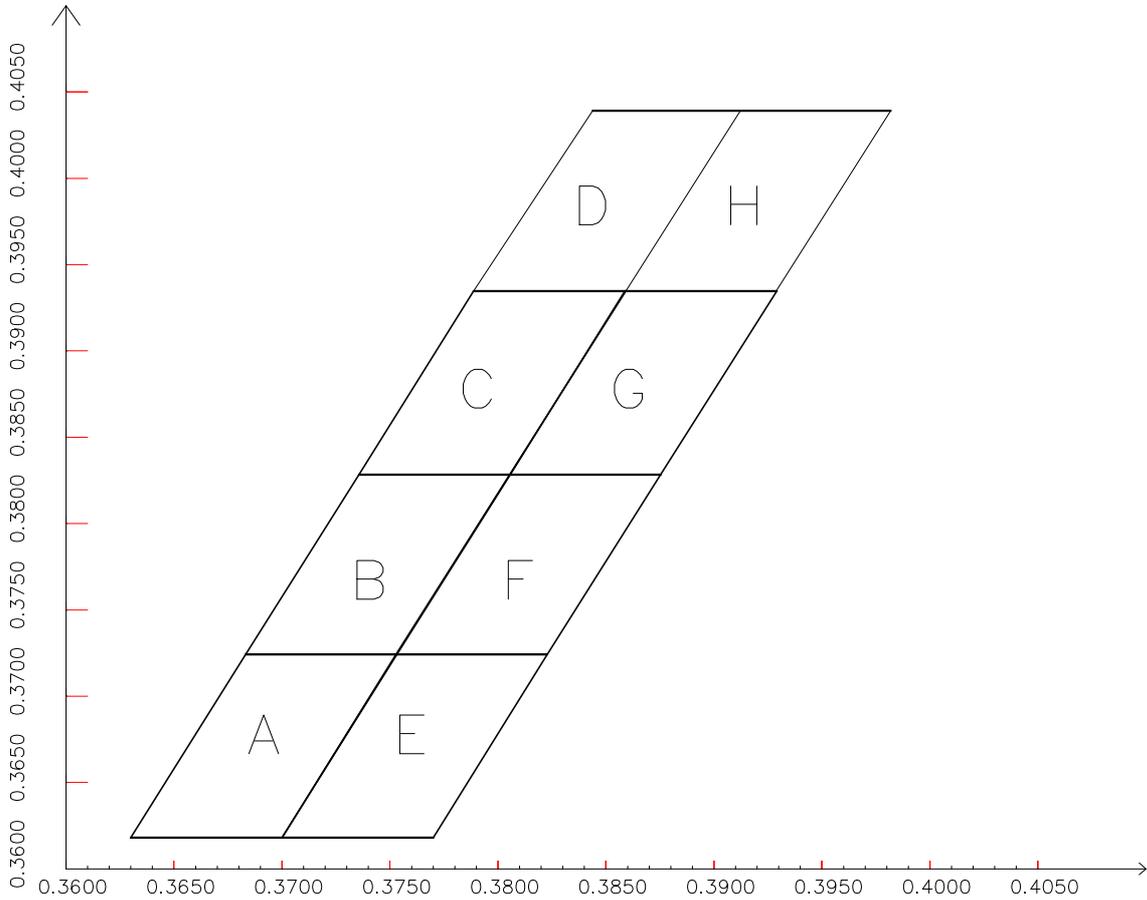


辐射曲线图

Radiation curve



BIN 区分类及色坐标范围:



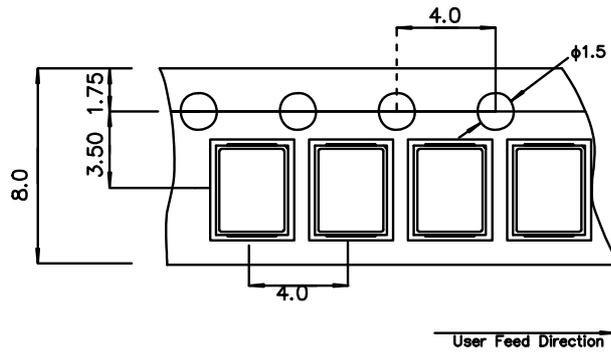
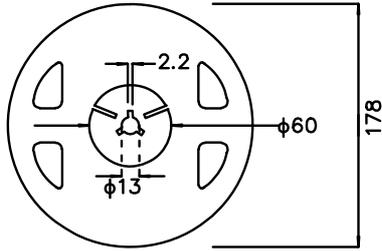
色区坐标: (测量公差: $X:\pm 0.0053$)

	X1	y1	X2	y2	X3	y3	X4	y4
A	0.3630	0.3619	0.3683	0.3724	0.3753	0.3724	0.3700	0.3619
B	0.3683	0.3724	0.3636	0.3829	0.3806	0.3829	0.3753	0.3724
C	0.3736	0.3829	0.3789	0.4034	0.3859	0.3934	0.3806	0.3829
D	0.3789	0.3934	0.3742	0.4039	0.3912	0.4039	0.3859	0.3934
E	0.3700	0.3619	0.3753	0.3724	0.3823	0.3724	0.3770	0.3719
F	0.3753	0.3724	0.3806	0.3829	0.3876	0.3829	0.3823	0.3724
G	0.3806	0.3829	0.3859	0.3934	0.3929	0.3934	0.3876	0.3829
H	0.3859	0.3934	0.3912	0.4039	0.3982	0.4039	0.3929	0.3934

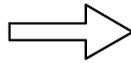
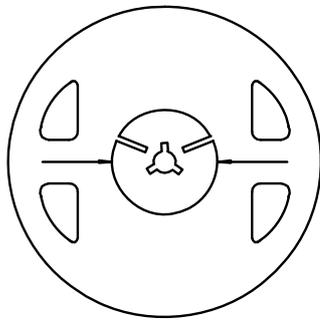
信赖度测试/ Reliability Test:

类别 Classification	测试项目 Test Item	测试环境 Test Condition	测试时间 Test time	参考标准 Reference Standard
耐久性测试 Endurance Test	工作寿命 Operation Life	室温条件下以最大额定电流持续点亮, 以60mA测试. Ta= Under Room Temperature As Per Data Sheet Maximum Rating	1000 HRS (-24 HRS, +72 HRS)	MIL-STD-750 D:1026 MIL-STD-883 D:1005
	高温高湿储存 High Temperature, High Humidity Storage	IR-Reflow In-Board, 2 Times 环境温度 Ta= 85℃, RH= 85% IR-Reflow In-Board, 2 Times Ta= 85℃, RH= 85%	1000 HRS (± 2 HRS)	JESD22-A101
	高温储存 High Temperature Storage	环境温度 Ta= 105±5℃	1000 HRS (-24HRS, +72 HRS)	MIL-STD-883 D:1008 JIS C 7021:B-10
	低温储存 Low Temperature Storage	环境温度 Ta= -40±5℃	1000 HRS (-24HRS, +72 HRS)	JIS C 7021:B-10
环境测试	温度循环 Temperature Cycling	100℃ ~25℃ ~ -40℃ ~25℃ 30mins 5mins 30mins 5mins	100次循环/ Cycles	MIL-STD-202F:107D MIL-STD-750D:1051
	冷热冲击 Thermal Shock	IR-Reflow In-Board, 2 Times 100 ± 5℃ ~ -40℃ ± 5℃ 10mins 10mins	100次循环/ Cycles	MIL-STD-202F:107D MIL-STD-750D:1051
	回流焊无铅制程 Reflow Pb Free Process	温度最高260℃: 最大10秒 Peak temperature range 260℃ 10s max	-----	MIL-STD-750 D:2031.2 J-STD-020C

包装载带与圆盘尺寸 / Reel And Tape Dimensions

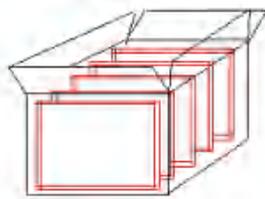
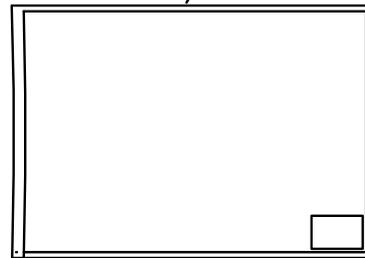


包装 / Packaging

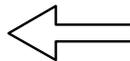


防潮防静电袋 / Aluminum moisture-proof bag

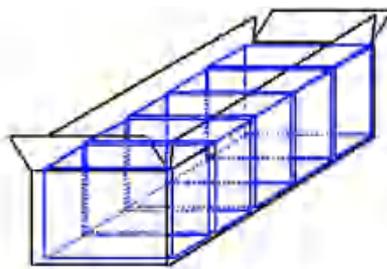
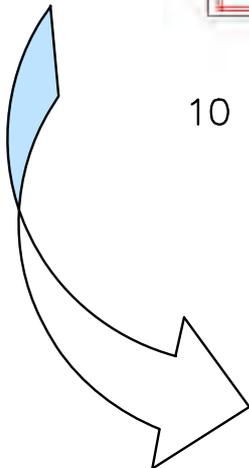
外标签 / Label



10 bags/carton (袋/盒)

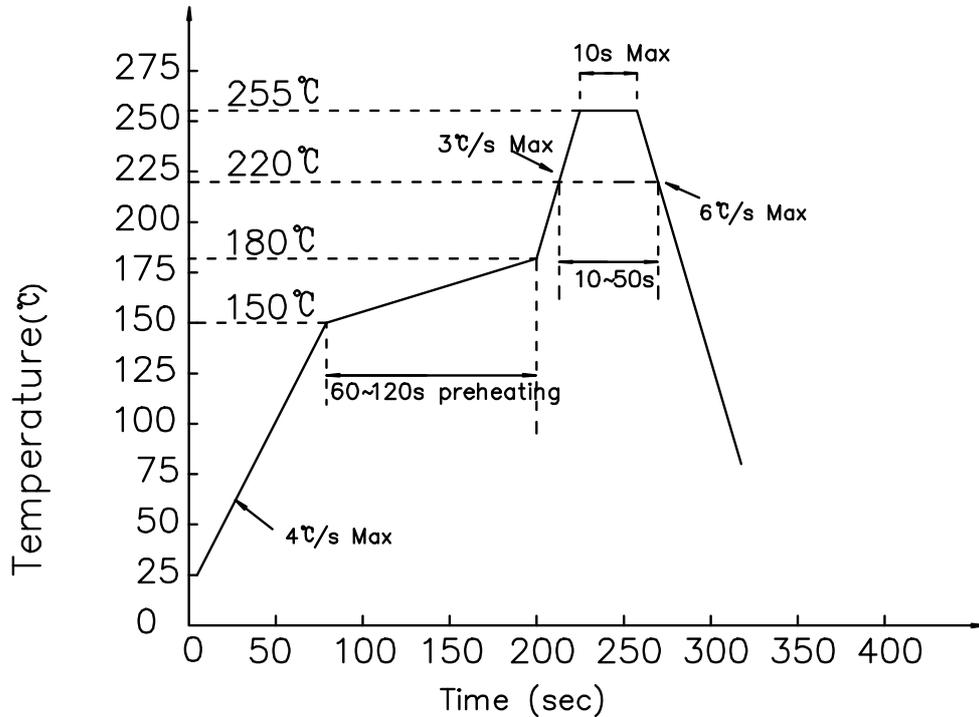


热封 / Sealing



5 carton/box (盒/箱)

建议焊接温度曲线 / Soldering Profile Suggested



无铅焊接 / For Lead Free Solder

焊接 / Soldering

1. 回流焊焊接次数不得超过两次。

Reflow soldering should not be done more than 2 times.

2. 只建议在修理和重工的情况下使用手工焊接；最高焊接温度不应超过300度，

且须在3秒内完成。烙铁最大功率应不超过30W。

Manual soldering is only suggested on repair and rework. The maximum soldering temperature should not exceed 300°C within 3 sec. And the maximum capacity of soldering iron is 30W in power.

3. 焊接过程中，严禁在高温情况下碰触胶体。

During the soldering process, do not touch the lens at high temperature.

4. 焊接后，禁止对胶体施加外力，禁止弯折PCB，避免元件受到撞击。

After soldering, any mechanical force on the lens or any excessive vibration shall not be accepted to apply, also the circuit board shall not be bent as well.